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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/795,979	03/10/2004	Dong-wook Kim	249/437	2293
27849	7590	03/23/2006		EXAMINER
LEE & MORSE, P.C. 1101 WILSON BOULEVARD SUITE 2000 ARLINGTON, VA 22209			QUASH, ANTHONY G	
			ART UNIT	PAPER NUMBER
			2881	

DATE MAILED: 03/23/2006

Please find below and/or attached an Office communication concerning this application or proceeding.



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APPLICATION NO./ CONTROL NO.	FILING DATE	FIRST NAMED INVENTOR / PATENT IN REEXAMINATION	ATTORNEY DOCKET NO.
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EXAMINER

ART UNIT PAPER

20060316

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Commissioner for Patents

EXAMINER'S AMENDMENT

An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

Authorization for this examiner's amendment was given in a telephone interview with Ms. Susan Werbow, representative for Ms. Susan Morse, on 3/16/06.

The application has been amended as follows:

Delete current claim 21 and insert its' place – A method of fabricating an electron beam lithography apparatus, comprising: preparing a pyroelectric plate; preparing a patterned mask of a semiconductor material, including sequentially forming a semiconductor thin film having a predetermined thickness and a resist on a dielectric plate having the predetermined thickness, patterning the resist in a predetermined pattern, patterning the semiconductor thin film using the patterned resist as a mask, and removing the patterned resist, the semiconductor material being sufficiently thick in desired portions to prevent electrons emitted by the pyroelectric plate during heating from being further transmitted; disposing the patterned mask adjacent the surface of the pyroelectric plate; providing a heating source for heating the pyroelectric emitter; and providing a pair of magnets disposed beyond the pyroelectric emitter and the substrate holder, respectively, to control paths of electrons emitted by the pyroelectric emitter.—
Cancel claim 22.


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